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Swiss energy research for the energy transition

DeCarbCH

Goals

Decarbonizing Swiss Pulp and Paper Industry

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Problem

Assessing Energy-Saving Opportunities at Each Site

Conducting Pinch Analysis for Heat Recovery Potential

Minimizing Utility Usage

Prioritizing Electrification in Processes and Utilities

Evaluating High-Temperature Heat Pump Integration

Unlocking Heat Recovery Potential in Paper Manufacturing Industry

- Analyzing Heat Demands and Optimal **Temperature Targets**
- Evaluating the Viability of Maximizing Heat Recovery
- Assessing the Integration of High-Temperature Heat Pumps
- Cost-benefit analysis of Energy Retrofits and Upgrades







Introduction

- Industry's Share: 19% of Switzerland's Final Energy
- Pulp & Paper's Slice: Roughly 9% of National Industrial Final Energy
- **Rising paper demand:** Makes decarbonization more challenging & urgent
- **Dominant Duo:** Model AG & Perlen Papier produce 90% of Swiss Paper
- **Pinch Analysis:** Shows potential of energy savings in paper mills
- Heat Recovery Opportunity: Potential of 58 MW identified
- Demand vs. Waste acc. to Pinch Analysis: 93 MW Needed, 111 MW Waste Heat Recoverable from 48°C to Ambient (cooling needs)
- Steam Efficiency: 150°C Steam fulfilling over 85% of Demand



Conclusions

- Pinch analysis reveals up to 39% of heat demand can be met through heat recovery.
- PBP for the IWL is 1-2 years, while for the entire system, it extends to 5 years.
- Full system adoption cuts final energy demand by 39% and CO_2 emissions by 96% (-215 kt CO₂).
- PBP for the IWL is highly sensitive to gas price and the cost of heat exchangers.
- HTHP with Internal Heat Exchangers and/or Intercoolers are optimal for the paper industry.
- Approx. 30 MW waste heat can be upgraded for thermal grids using market-available HP.

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